



**RoHS Compliant**

REV	MODIFICATION	DATE	DRAW
A0	Release To ECN20150703	2015.07.15	Michelle
A1	Release To ECN20150808	2015.08.24	Michelle

- Specification**
- 1.Current Rating:3A AC/DC
  - 2.Voltage Rating:250V AC/DC
  - 3.Contact Resistance:20mΩ Maximum
  - 4.Insulation Resistance:1000MΩ Min. At DC 500V
  - 5.Dielectric Withstanding Voltage:AC1000V/Minute
  - 6.Operating Temperature:-25°C~+85°C

- Material:**
- 1.Housing:High Temperature Thermoplastic UL94V-2
  - 2.Contact Pin:Copper Alloy SQ. Pin 0.64mm
- Finish:**
- 1.Housing:Natural
  - 2.Contact Pin:See P/N Option
- Part No.: AD03601 XX 1 X 5 2
- No. Of Pin: 02~20      Packing: 5:Bag
- Housing Material: 1:Nylon66 UL94V-2 Natural
- Plating: 1:Bright Tin Plated Over Nickel  
2:Matte Tin Plated Over Nickel  
3:Gold Plated Over Nickel

PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B
02	2.54	5.12	07	15.24	17.94	12	27.94	30.68	17	40.64	43.30
03	5.08	7.66	08	17.78	20.48	13	30.48	33.10	18	43.18	45.90
04	7.62	10.20	09	20.32	23.02	14	33.02	35.80	19	45.72	48.56
05	10.16	12.74	10	22.86	25.58	15	35.56	38.34	20	48.26	50.80
06	12.70	15.30	11	25.40	28.12	16	38.10	40.94			

**金上達科技股份有限公司**  
GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED	PROJ.	TITLE: Wire To Board Wafer 2.54mm 90° DIP Single Row	
.x± 0.35    x.*± 2'	APR. C.F.Liao 20150824	PART NO. AD03601XX1X52	DWG NO. AD03601XX1X52
.xx± 0.25    .x.*± 1'	CHK. Abel 20150824	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15    .xx.*± 0.5'	DRA. Michelle 20150824	SIZE: A4	SCALE 4:1    SHEET 1 / 1    REV A1    V